



Material Content Data Sheet



Sales Product Name		BTT6050-1EKA		Issued		29. August 2013		
MA#		MA001134404						
Package		PG-DSO-14-47		Weight*		150.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.990	1.32	1.32	13249	13249
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		461	
	non noble metal	iron	7439-89-6	1.383	0.92		9211	
wire	non noble metal	copper	7440-50-8	56.175	37.40	38.38	374006	383793
	non noble metal	copper	7440-50-8	0.483	0.32	0.32	3214	3214
	organic material	carbon black	1333-86-4	0.171	0.11		1137	
encapsulation	plastics	epoxy resin	-	7.859	5.23		52325	
	inorganic material	silicondioxide	60676-86-0	77.394	51.54	56.88	515282	568744
leadfinish	non noble metal	tin	7440-31-5	2.472	1.65	1.65	16456	16456
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9789	9789
glue	plastics	epoxy resin	-	0.125	0.08		832	
	noble metal	silver	7440-22-4	0.589	0.39	0.47	3923	4755
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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